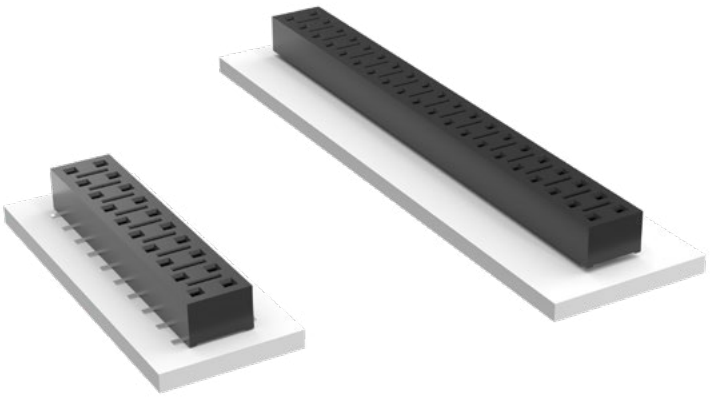
TIGER™ BEAM CONTACT

COST-EFFECTIVE RELIABLE SOCKET



(2.54 mm) .100" PITCH • HLE SERIES

HLE
Board Mates:
TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW

HLE	-	1	NO. PINS PER ROW	-	02	-	PLATING OPTION	-	DV	-	TAIL OPTION	-	OTHER OPTION

02 thru 50

–F
= Gold flash on contact, Matte Tin on tail

–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

Leave blank for Surface Mount (Requires –BE for Bottom Entry)

–TE
= Through-hole Top Entry

–PE
= Through-hole Pass-through Entry (Requires –BE for Bottom Entry)

–BE
= Bottom Entry (Not available with –TE)

–A
= Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (Not available with -TE, -PE & -LC)

–LC
= Locking Clip (2 positions min.) (Not available with -A) (Manual placement required)

–K
= (6.50 mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with –TE or –PE tail option

–P
= Metal Pick & Place Pad (3 positions min.)

–TR
= Tape & Reel (29 positions max.)

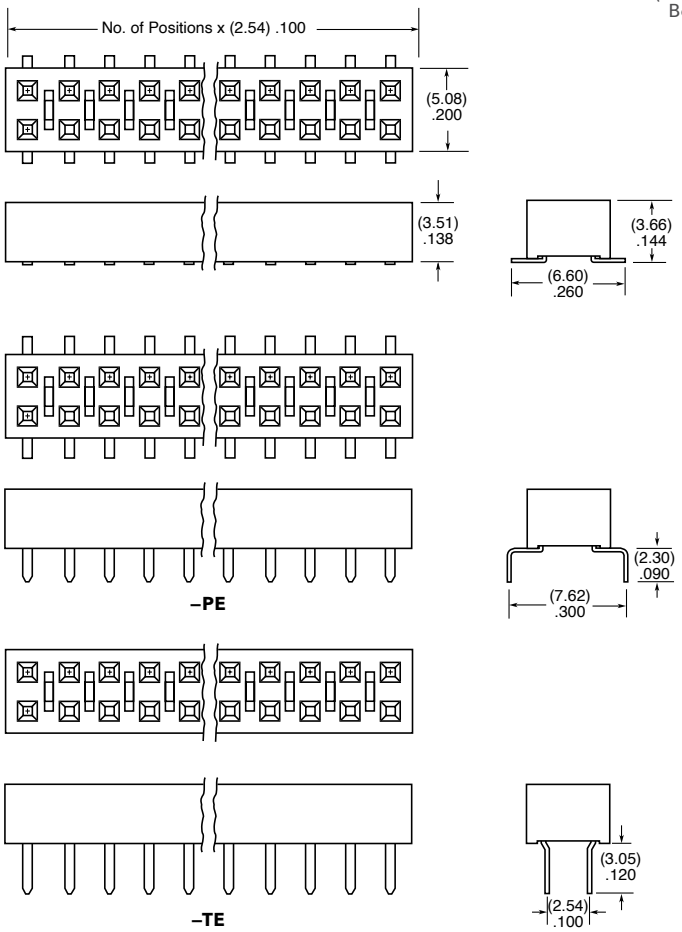
–FR
= Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

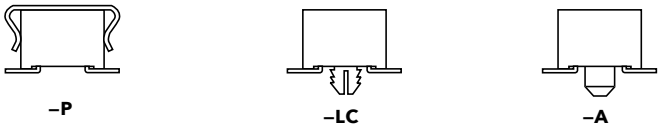
SPECIFICATIONS

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
BeCu
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating (HLE/TSM):
4.1 A per pin
(2 pins powered)
Voltage Rating:
400 VAC
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(1.78 mm) .070" to
(3.43 mm) .135" pass-through,
or (2.59 mm) .102" min
plus board thickness for
bottom entry

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-20)
(0.15 mm) .006" max (21-50)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)





ALSO AVAILABLE
MOQ Required

Other Platings

Note:
Some lengths, styles and options are non-standard, non-returnable.

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.